

Silicon Carbide Power MOSFET C3M™ MOSFET Technology N-Channel Enhancement Mode

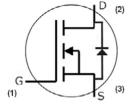
Features

- 3rd generation SiC MOSFET technology
- High blocking voltage with low On-resistance
- High speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery (Q_{rr})
- Halogen free, RoHS compliant





RoHS



1 2 3

Wolfspeed, Inc. is in the process of rebranding its products and related materials pursuant to the entity name change from Cree, Inc. to Wolfspeed, Inc. Dring this transition period, products received may be marked with either the Cree name and/or logo or the Wolfspeed name and/or logo.

Part Number	Package	Marking
C3M0032120D	TO 247-3	C3M0032120D

Typical Applications

- Solar inverters
- EV motor drive
- High voltage DC/DC converters
- Switched mode power supplies

Benefits

- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

Key Parameters

Parameter	Symbol	Min.	Тур.	Max	Unit	Conditions	Note
Drain - Source Voltage	V _{DS}			1200		T _c = 25°C	
Maximum Gate - Source Voltage	V _{GS(max)}	-8		+19	v	Transient	
Operational Gate-Source Voltage	V _{GS op}		-4/15			Static	Note 1
DC Continuous Drain Current				63		$V_{GS} = 15 \text{ V}, T_{C} = 25 \text{ °C}, T_{J} \le 175 \text{ °C}$	Fig. 19 Note 2
	l l _D			48	Α	$V_{GS} = 15 \text{ V}, T_{C} = 100 \text{ °C}, T_{J} \le 175 \text{ °C}$	
Pulsed Drain Current	I _{DM}			120		t _{Pmax} limited by T _{jmax} V _{GS} = 15V, T _C = 25 °C	Fig. 22
Power Dissipation	P _D			283	w	$T_{c} = 25^{\circ} C, T_{J} = 175^{\circ} C$	Fig. 20
Operating Junction and Storage Temperature	T_J , T_{stg}			-40 to +175	°C		
Solder Temperature	T _L			260		According to JEDEC J-STD-020	
Mounting Torque	M _D			1 8.8	Nm Ibf-in	M3 or 6-32 screw	

 $Note~(1): Recommended~turn-on~gate~voltage~is~15V~with~\pm 5\%~regulation~tolerance, see~Application~Note~PRD-04814~for~additional~details~tolerance, see~Application~details~tolerance, see~Applicat$

Note (2): Verified by design

Electrical Characteristics ($T_c = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Conditions	Note	
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200	_	_		$V_{GS} = 0 \text{ V}, I_{D} = 100 \mu\text{A}$		
	N.	1.8	2.5	3.6	V	$V_{DS} = V_{GS}$, $I_{D} = 11.5 \text{ mA}$	F: 44	
Gate Threshold Voltage	$V_{GS(th)}$	_	2.0	_		$V_{DS} = V_{GS}$, $I_D = 11.5$ mA, $T_J = 175$ °C	Fig. 11	
Zero Gate Voltage Drain Current	I _{DSS}	_	1	50	μΑ	V _{DS} = 1200 V, V _{GS} = 0 V		
Gate-Source Leakage Current	I _{GSS}	_	10	250	nA	V _{GS} = 15 V, V _{DS} = 0 V		
Durin Course On State Pacietones		23	32	43	0	$V_{GS} = 15 \text{ V}, I_D = 40 \text{ A}$	Fig. 4, 5, 6	
Drain-Source On-State Resistance	R _{DS(on)}	_	57.6	_	mΩ	$V_{GS} = 15 \text{ V}, I_D = 40 \text{ A}, T_J = 175^{\circ}\text{C}$		
Transcenductores	_		27			V _{DS} = 20 V, I _{DS} = 40 A	Fig. 7	
Transconductance	g fs	_	22	_	S	V _{DS} = 20 V, I _{DS} = 40 A, T _J = 175°C		
Input Capacitance	C _{iss}	_	3357	_		V 0V	Fig. 17, 18	
Output Capacitance	Coss	_	129	_	pF	$V_{GS} = 0 V,$ $V_{DS} = 1000 V$		
Reverse Transfer Capacitance	C _{rss}	_	8	_		f = 100 khz $V_{AC} = 25 \text{ mV}$		
C _{oss} Stored Energy	E _{oss}	_	76	_	μJ	V _{AC} - 25 IIIV	Fig. 16	
Turn-On Switching Energy (SiC Diode FWD)	Eon	_	1.94	_				
Turn Off Switching Energy (SiC Diode FWD)	E _{off}	_	0.79	_		$V_{DS} = 800 \text{ V}, V_{GS} = -4/+15 \text{ V}, I_{D} = 40 \text{ A},$		
Turn-On Switching Energy (Body Diode FWD)	E _{on}	_	3.10	_	mJ $R_{G(ext)} = 5 \Omega$, L= 157 μ H, T _J = 175°C		Fig. 26	
Turn Off Switching Energy (Body Diode FWD)	E _{off}	_	0.72	_				
Turn-On Delay Time	t _{d(on)}	_	107	_		V 000 V V 4/4 F V		
Rise Time	t _r	_	22	_		$V_{DS} = 800 \text{ V}, V_{GS} = -4/15 \text{ V}$ $R_{G(ext)} = 5 \Omega, I_D = 40 \text{ A}, L = 157$		
Turn-Off Delay Time	t _{d(off)}	_	39	_	ns Timing relative to V _{DS} ,		Fig. 27	
Fall Time	t _f	_	19	_		inductive toad		
Internal Gate Resistance	R _{G(int)}	_	1.7	_	Ω	f = 1 MHz, V _{AC} = 25 mV		
Gate to Source Charge	$Q_{\rm gs}$	_	35	_	V _{DS} = 800 V, V _{GS} = -4 V/15 V			
Gate to Drain Charge	$Q_{\rm gd}$	_	40	_	nC	I _D = 40 A	Fig. 12	
Total Gate Charge	Qg	_	114	_		Per IEC60747-8-4 pg 21		

Reverse Diode Characteristics ($T_c = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Тур.	Max.	Unit	Test Conditions	Note	
Diode Forward Voltage	V	4.6	_	V	$V_{GS} = -4 \text{ V}, I_{SD} = 20 \text{ A}, T_{J} = 25^{\circ}\text{C}$	Fig.	
	V_{SD}	4.2	_		$V_{GS} = -4 \text{ V}, I_{SD} = 20 \text{ A}, T_J = 175^{\circ}\text{C}$	8, 9, 10	
Continuous Diode Forward Current	Is	_	62		V _{GS} = -4 V, T _C = 25°C		
Diode Pulse Current	I _{SM}	_	120	A	V_{GS} = -4 V, T_C = 25°C, pulse width limited by T_{imax}		
Reverse Recover Time	t _{rr}	69	_	nS			
Reverse Recovery Charge	Qrr	848	_	nC	$V_{GS} = -4 \text{ V}, I_{SD} = 40 \text{ A}, V_{R} = 800 \text{ V}$ - $di_{F}/dt = 1500 \text{ A}/\mu\text{s}, T_{J} = 175^{\circ}\text{C}$		
Peak Reverse Recovery Current	I _{rrm}	19	_	Α	- αιματ – 1300 γγμ3, 13 – 173 €		

Thermal Characteristics

Parameter	Symbol	Тур.	Unit	Note
Thermal Resistance from Junction to Case	$R_{ heta JC}$	0.45	°C/W	Fi- 21
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	40	C/W	Fig. 21

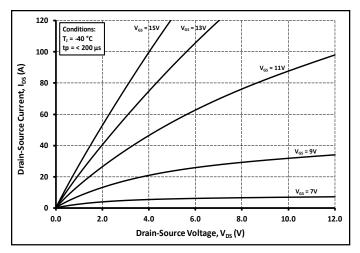


Figure 1. Output Characteristics $T_1 = -40^{\circ}C$

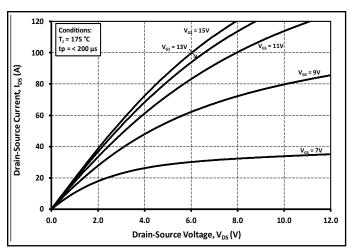


Figure 3. Output Characteristics T_J = 175°C

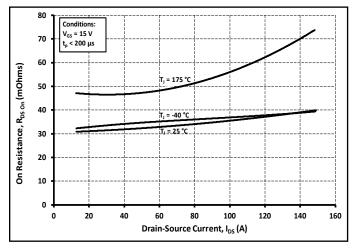


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

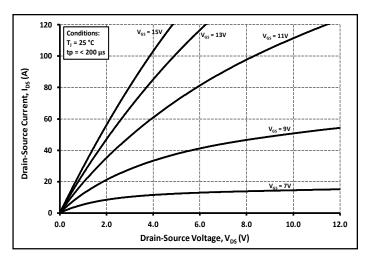


Figure 2. Output Characteristics T_J = 25°C

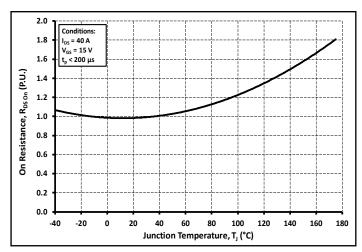


Figure 4. Normalized On-Resistance vs. Temperature

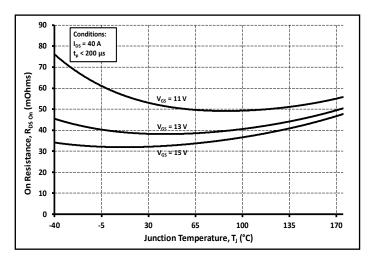


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

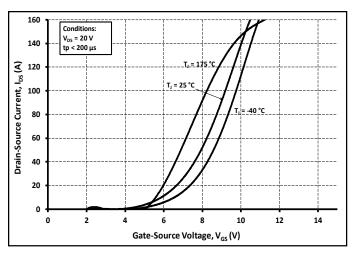


Figure 7. Transfer Characteristic for Various Junction Temperatures

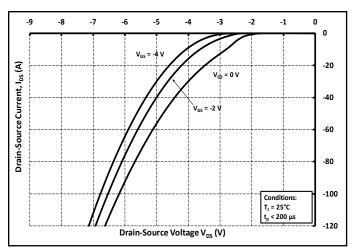


Figure 9. Body Diode Characteristic at 25°C

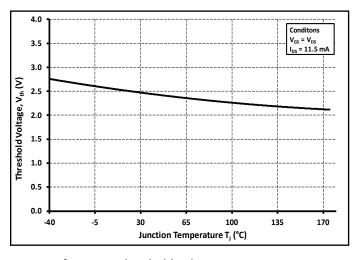


Figure 11. Threshold Voltage vs. Temperature

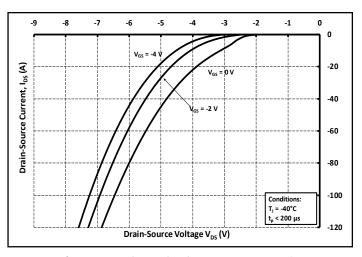


Figure 8. Body Diode Characteristic at -40°C

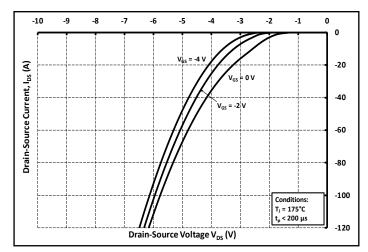


Figure 10. Body Diode Characteristic at 175°C

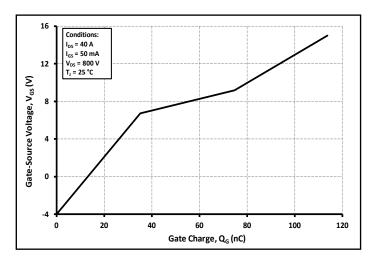


Figure 12. Gate Charge Characteristics

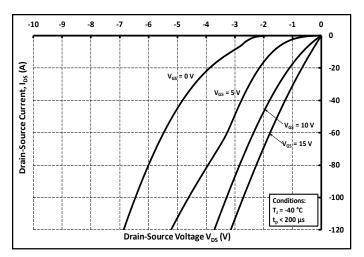


Figure 13. 3rd Quadrant Characteristic at -40°C

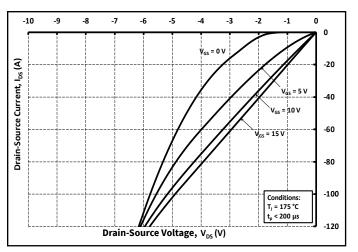


Figure 15. 3rd Quadrant Characteristic at 175°C

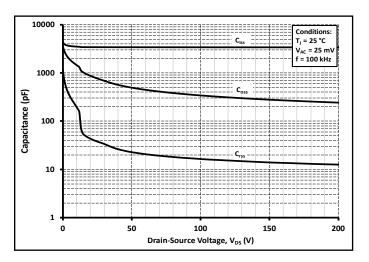


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200 V)

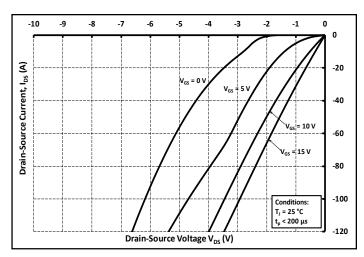


Figure 14. 3rd Quadrant Characteristic at 25°C

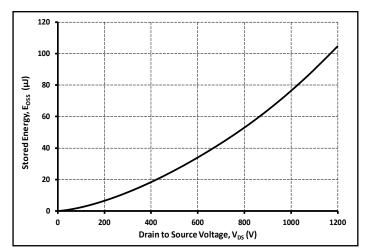


Figure 16. Output Capacitor Stored Energy

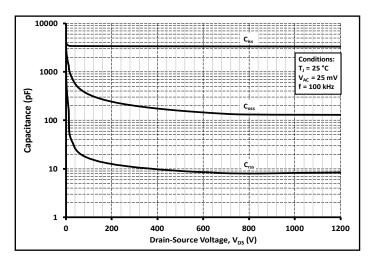


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1200 V)

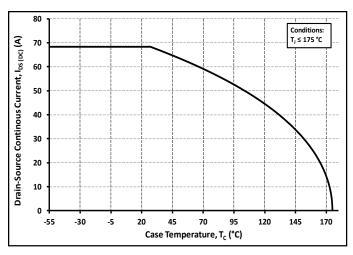


Figure 19. Continuous Drain Current Derating vs. Case Temperature

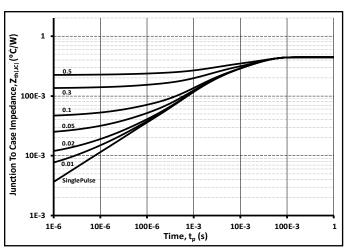


Figure 21. Transient Thermal Impedance (Junction - Case)

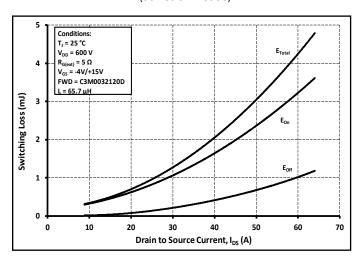


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 600 \text{ V}$)

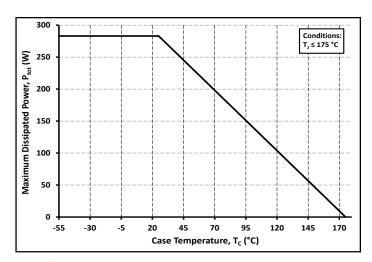


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

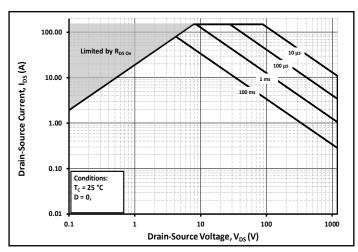


Figure 22. Safe Operating Area

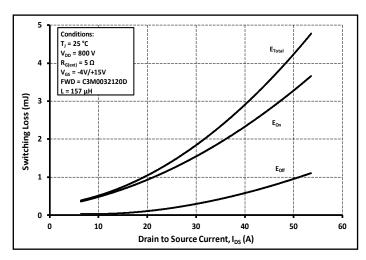


Figure 24. Clamped Inductive Switching Energy vs. Drain Current $(V_{DD} = 800 \text{ V})$

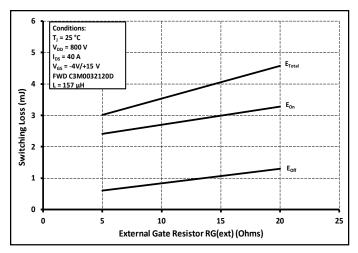


Figure 25. Clamped Inductive Switching Energy vs. R_{G(ext)}

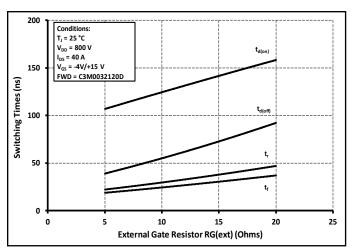


Figure 27. Switching Times vs. R_{G(ext)}

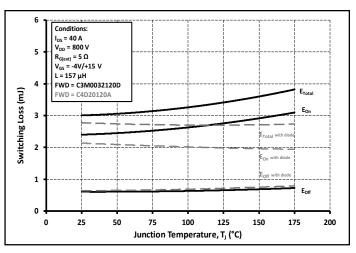


Figure 26. Clamped Inductive Switching Energy vs. Temperature

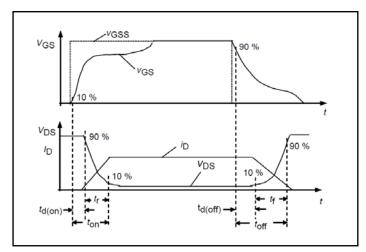


Figure 28. Switching Times Definition

Test Circuit Schematic

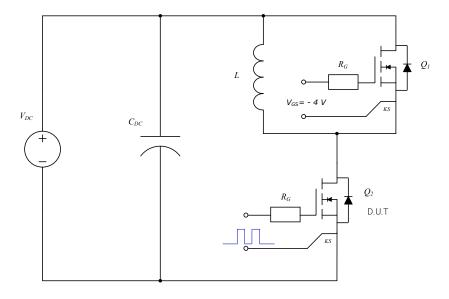
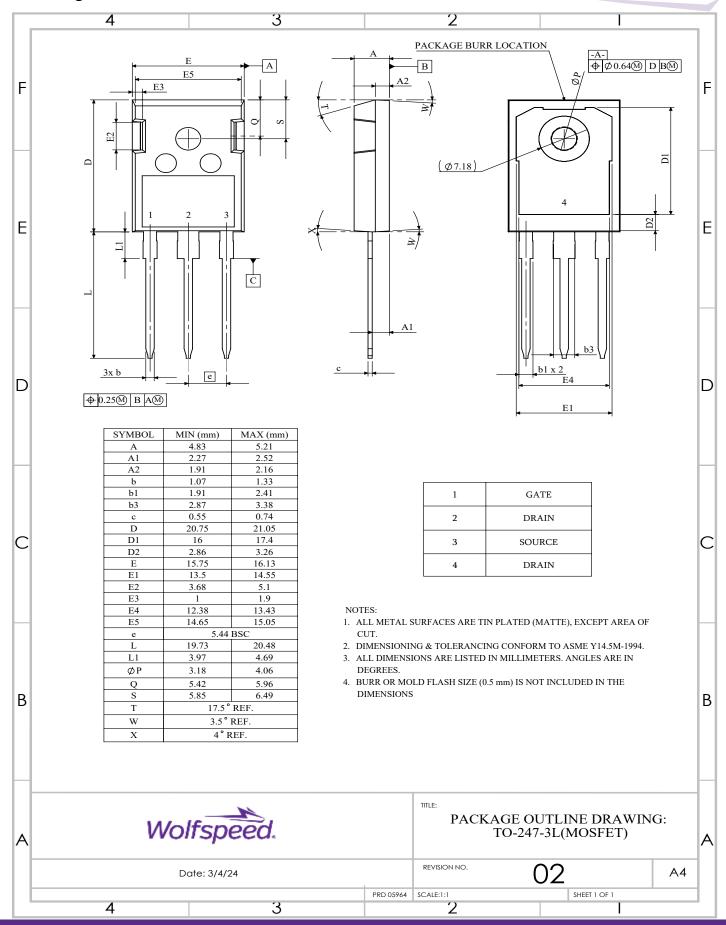


Figure 29. Clamped Inductive Switching Waveform Test Circuit

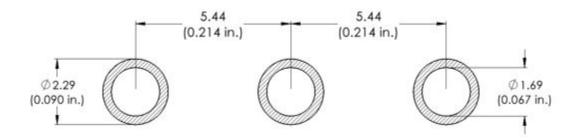
Note

³ Turn-off and Turn-on switching energy and timing values measured using SiC MOSFET Body Diode as shown above.

Package Dimensions - TO-247-4L



Recommended Solder Pad Layout



Revision History

Current Revision	Date of Release	Description of Changes
-	December-2019	N/A
1	January-2024	Updated Wolfspeed branding, package drawing, package image, and solder pad layout, added Revision History Table. Table 1 layout revised
2	September - 2024	Legal Disclaimer, POD, Diode Pulse Current Symbol
3	March - 2025	Fig 20 corrected

Related Links

- SPICE Models: http://wolfspeed.com/power/tools-and-support
- <u>SiC MOSFET Isolated Gate Driver Reference Design</u>: http://wolfspeed.com/power/tools-and-support
- <u>SiC MOSFET Evaluation Board</u>: http://wolfspeed.com/power/tools-and-support

Notes & Disclaimer

WOLFSPEED PROVIDES TECHNICAL AND RELIABILITY DATA, DESIGN RESOURCES, APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, WITH RESPECT THERETO, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, SUITABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD-PARTY INTELLECTUAL PROPERTY RIGHTS.

This document and the information contained herein are subject to change without notice. Any such change shall be evidenced by the publication of an updated version of this document by Wolfspeed. No communication from any employee or agent of Wolfspeed or any third party shall effect an amendment or modification of this document. No responsibility is assumed by Wolfspeed for any infringement of patents or other rights of third parties which may result from use of the information contained herein. No license is granted by implication or otherwise under any patent or patent rights of Wolfspeed.

The information contained in this document (excluding examples, as well as figures or values that are labeled as "typical") constitutes Wolfspeed's sole published specifications for the subject product. "Typical" parameters are the average values expected by Wolfspeed in large quantities and are provided for informational purposes only. Any examples provided herein have not been produced under conditions intended to replicate any specific end use. Product performance can and does vary due to a number of factors.

This product has not been designed or tested for use in, and is not intended for use in, any application in which failure of the product would reasonably be expected to cause death, personal injury, or property damage. For purposes of (but without limiting) the foregoing, this product is not designed, intended, or authorized for use as a critical component in equipment implanted into the human body, life-support machines, cardiac defibrillators, and similar emergency medical equipment; air traffic control systems; or equipment used in the planning, construction, maintenance, or operation of nuclear facilities. Notwithstanding any application-specific information, guidance, assistance, or support that Wolfspeed may provide, the buyer of this product is solely responsible for determining the suitability of this product for the buyer's purposes, including without limitation (1) selecting the appropriate Wolfspeed products for the buyer's application, (2) designing, validating, and testing the buyer's application, and (3) ensuring the buyer's application meets applicable standards and any other legal, regulatory, and safety-related requirements.

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Wolfspeed representative or from the Product Documentation sections of www.wolfspeed. com.

REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact your Wolfspeed representative to ensure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

Contact info:

4600 Silicon Drive Durham, NC 27703 USA Tel: +1.919.313.5300 www.wolfspeed.com/power